AN-694

## Hot Swap and Blocking FET Controller $2 \times$ ADM1073 Hot Swap Controllers

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## INTRODUCTION

In many -48 V hot swap systems, there is a blocking diode in series with the hot swapping FET. This component ensures that current can only flow into the load in one direction, preventing damage to the board in the case of reverse currents flowing. Figure 1 shows this implementation in an ADM1073 controlled system.
This solution can have serious power dissipation implications during normal operation due to the voltage drop across the blocking diode

$$
P_{\text {LOSS }}=P_{\text {FET }}+P_{\text {DIODE }}+P_{\text {QUIIESCENT }}
$$

where:
$P_{\text {DIODE }}=($ Load Current $) \times($ Diode Voltage Drop $)$
Note that $\mathrm{P}_{\text {DIode }}$ is responsible for a substantial portion of the total power loss (see Figure 1).

This is especially evident in applications where the average load current level is high and the total power losses are calculated across an entire system, which may consist of multiple racks of boards.


Figure 1. Blocking Diode in Series with Hot Swap FET

## ALTERNATIVE SOLUTION

This application note focuses on another solution for systems where this power loss is unacceptable. The alternative solution is to replace the blocking diode with a blocking FET that has a low on resistance. A second ADM1073 can control this blocking FET. Figure 2 shows this solution on a plug-in board.

This solution reduces the power dissipation during operation to

$$
P_{\text {LOSS }}=P_{\text {HSWAP-FET }}+P_{\text {BLK-FET }}+P_{Q U I E S C E N T}
$$

where:
$P_{\text {BLK-FET }}=(\text { Load Current })^{2} \times($ FET On Resistance $)$
Note that $\mathrm{P}_{\text {ble-fet }}$ is much smaller than $\mathrm{P}_{\text {diode }}$ and therefore reduces the total power loss significantly.

The ADM1073 data sheet should be consulted in conjunction with this application note.


Figure 2. Alternative Solution-Blocking FET Replaces Diode

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## REVISION HISTORY

5/13-Rev. 0 to Rev. A
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11/03-Revision 0: Initial Version


Figure 3. Full Implementation of Dual ADM1073 Solution for Blocking FET and Hot Swap FET Control

## DETAILED DESCRIPTION

Figure 3 shows a full implementation of a dual ADM1073 solution for a blocking FET and hot swap FET control.

FET1 is the hot swap FET. This device must also have a low on resistance and a high reverse voltage capability. This device is required to dissipate high power during startup, so a D2PAK device may be required. ADM1073 (A) is the hot swap FET controller that controls FET1.
FET2 is the blocking FET. This device must have low on resistance to minimize power dissipation and a high reverse voltage capability. This device does not have to dissipate as much power so a smaller package may be suitable (for example, SOIC). ADM1073 (B) is the blocking FET controller that controls FET2.

A single sense element, Rensse, can be used for both ADM1073 devices. With this method, the ADM1073 (A) limits forward load current to $100 \mathrm{mV} / \mathrm{R}_{\text {SENSE }}$; the ADM1073 (B) limits reverse load current to $18 \mathrm{mV} / 100 \mathrm{mV}$.

## Example Configuration for ADM1073 (A)

The undervoltage level is set by R5 and R6. R5 is $500 \mathrm{k} \Omega$; R6 is $15 \mathrm{k} \Omega$. R6 normally gives a UV rising threshold of 32.3 V and a UV falling threshold of 29.8 V . In this case, the UV rising level is actually $32.9 \mathrm{~V}+$ FET1 body diode voltage drop $(\sim 1 \mathrm{~V})$ and UV falling level will be $29.8 \mathrm{~V}+\mathrm{I}^{2} \mathrm{R}$ of FET2.
The overvoltage level is set by R3 and R4. R3 is $400 \mathrm{k} \Omega$; R4 is $10.7 \mathrm{k} \Omega$. R4 normally gives an OV rising threshold of 74.08 V and an OV falling threshold of 72.08 V . In this case, the OV falling level is actually $72.08 \mathrm{~V}+$ FET2 body diode voltage drop $(\sim 1 \mathrm{~V})$ and the OV rising level is $74.08 \mathrm{~V}+\mathrm{I}^{2} \mathrm{R}$ of FET1.
The soft start time is set by Css. $\mathrm{C}_{\mathrm{ss}}=2.2 \mathrm{nF} \geq \mathrm{t}_{\mathrm{ss}}=0.9 \mathrm{~ms}$. TIMER is selected by the $\mathrm{C}_{\text {TIMER }}$ capacitor, for example, $\mathrm{C}_{\text {TIMER }}=$ 82 nF gives a maximum TIMER of 5.8 ms at -48 V .

The drain fold back (for FET SOA protection) is set with RDrain. A $5 \mathrm{M} \Omega$ resistor is sufficient to charge a $470 \mu \mathrm{~F}$ load.
The R2 dropper resistor is set to $30 \mathrm{k} \Omega$ for normal operation.
The $\overline{\text { LATCHED }}$ output is tied back to the $\overline{\text { RESTART }}$ input to give a continuous retry with a 5 second cooling off period under short-circuit condition.
The $\overline{\text { SHDN }}$ input is used as the start-up control if it is required.
The $\overline{\text { PWRGD }}$ output is used as a hot swap completion flag, which is required.
The $\overline{\text { SPLYGD }}$ output is connected to the OV pin of the ADM1073 (B) to provide a start-up signal to the ADM1073 (B) based on the voltage detection in the ADM1073 (A).

## Example Configuration for ADM1073 (B)

The SENSE and $V_{\text {EE }}$ pins connect across the ADM1073 (A) sense resistor with connections reversed, that is, the ADM1073 (B) SENSE pin is connected to the ADM1073 (A) $\mathrm{V}_{\text {EE }}$ pin and the ADM1073 (B) $\mathrm{V}_{\text {EE }}$ pin is connected to the ADM1073 (A) SENSE pin. This configures the ADM1073 (B) to regulate current in FET2 only if it sees a reverse current flowing in the sense resistor.
The undervoltage (UV) pin is tied to a resistor divider from the $\mathrm{V}_{\text {IN }}$ pin. Choose the resistor values so that the voltage on the UV pin is always above the UV threshold, for example, $\mathrm{R} 9=$ $500 \mathrm{k} \Omega ; \mathrm{R} 10=250 \mathrm{k} \Omega \geq \mathrm{V}_{\mathrm{UV}}=4 \mathrm{~V}$.
The overvoltage (OV) pin is connected to the $\overline{\text { SPLYGD }}$ output of the ADM1073 (A) so that startup of the ADM1073 (B) is controlled by the ADM1073 (A). A resistor to $\mathrm{V}_{\mathrm{EE}}$ on this pin ensures that the voltage on the OV pin does not exceed 5 V when the supply of the chip on the ADM1073 (A) is high (for example, $\mathrm{R} 8=800 \mathrm{k} \Omega \geq \mathrm{OV}=4 \mathrm{~V}$ when high plus pull-up from OV hysteresis, which brings it up to VCC of ADM1073 (B) but not above this).

The soft start (SS) pin is tied to $\mathrm{V}_{\mathrm{fe}}$. This fixes the reverse current control level at 18 mV , as opposed to up to 97.5 mV default. This limits the maximum reverse current to approximately $1 / 6^{\text {th }}$ of the forward inrush current limit.
The TIMER pin is left open. If reverse current is detected, it will current limit at $18 \mathrm{mV} / \mathrm{R}_{\text {sense }}$ for only a few microseconds plus the time taken to charge the gate up to $\mathrm{V}_{\text {GSth }}$ of the FET (the retry duty cycle should be less than $10 \%$ ). This then retries seven times and then shuts off, which should take no more than $\sim 0.5 \mathrm{~ms}$.
The DRAIN pin is unused and should be tied to $\mathrm{V}_{\mathrm{EE}}$.
The R1 dropper resistor is set to $30 \mathrm{k} \Omega$ for normal operation.
The $\overline{\text { LATCHED }}$ output is tied back to the $\overline{\text { RESTART }}$ input. If reverse current saturation persists for more than 0.5 ms , the blocking FET shuts off completely and then retries after 5 seconds (for example, if the input voltage is shorted for 100 ms , a small average reverse current would flow for 0.5 ms . The FET would switch off 5 seconds after the supply was good again, and the FET would turn back on and shunt the diode current).
The $\overline{\text { SHDN }}$ function is unused; leave the $\overline{\text { SHDN }}$ pin disconnected.
The $\overline{\text { PWRGD }}$ function is unused; leave the $\overline{\text { PWRGD }}$ pin disconnected.
The $\overline{\text { SPLYGD }}$ function is unused; leave the $\overline{\text { SPLYGD }}$ pin disconnected.

## Example Comparison for Power Dissipation Using Both Methods

Assumptions:
$\mathrm{I}_{\text {LOAD }}=5 \mathrm{~A}$
Ronfet $=10 \mathrm{~m} \Omega$
$\mathrm{V}_{\text {diode }}=1 \mathrm{~V}$

## Standard Diode Solution

Standard configuration using hot swap FET and blocking diode: Input lower $=96 \mathrm{~W}$
Hot swap power loss $=\mathrm{P}_{\text {fet }}+\mathrm{P}_{\text {diode }}+\mathrm{P}_{\text {Quiescent }}$
$=(5 \times 5 \times 0.01)+(5 \times 1)+(48 \times 0.0026)$
$=5.37 \mathrm{~W}$
(= $5.6 \%$ power loss)

## Dual ADM1073 Solution

New configuration using hot swap FET and blocking FET:
Input power $=96 \mathrm{~W}$
Hot swap power loss $=\mathrm{P}_{\text {hswap-fet }}+\mathrm{P}_{\text {ble-fet }}+\mathrm{P}_{\mathrm{Quiescent}}$
$=(5 \times 5 \times 0.01)+(5 \times 5 \times 0.01)+(48 \times 0.0026)$
$=0.62 \mathrm{~W}$
(= $0.65 \%$ total power loss)
Table 1. Results Based on Example Configurations

| Solution | Power Loss | Percentage Loss |
| :--- | :--- | :--- |
| Standard Diode Solution | 5.37 W | $5.6 \%$ |
| Dual ADM1073 Solution | 0.62 W | $0.65 \%$ |

